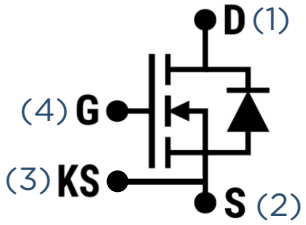
N3PT028MP120K
1200 V 28 mΩ Silicon Carbide MOSFET

V_{DS}	I_D	$R_{DS(on)}$	Package
1200 V	72 A	28 mΩ	TO-247-4

Features

- State-of-the-art SiC MOSFET technology
- Reliable gate oxide process
- 100% avalanche tested
- Low input capacitance
- Best-in-class figure-of-merits, [R_{on}*C_{iss}] and [R_{on}*C_{rss}]
- Stable switching characteristics up to 175 °C



(1) (2) (3) (4)

Benefits

- Higher system efficiency
- Reduced cooling requirements
- Increased power density
- Increased system switching frequency
- Enhanced system reliability
- Reduced total harmonic distortion

Applications

- Motor drives
- Solar PV inverters
- EV onboard chargers
- Server power supplies
- Energy storage systems
- EV fast charging stations
- Solid-state power controllers
- Uninterruptible power supplies

Maximum Ratings

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	Note
Drain-Source Voltage	$V_{(BR)DSS}$	T_C = 25 °C	1200	-	-	V	
Gate-Source Voltage	$V_{GS(max)}$		-10	-	25	V	
	$V_{GS,op}$	Recommended Operation	-	-5/+20	-		
Continuous Drain Current	I_D	V_{GS} = 20 V, T_C = 25 °C	-	-	72	A	Fig. 13
		V_{GS} = 20 V, T_C = 100 °C	-	-	51		
Pulsed Drain Current	$I_{D(pulse)}$	T_C = 25 °C	-	-	160	A	Fig. 12
Power Dissipation	P_{tot}	T_C = 25 °C	-	-	268	W	Fig. 14
Avalanche Energy, Single Pulse	E_{AS}	L = 26 mH, I_{AS} = 5.5 A	-	390		mJ	
Operating and Storage Temperature	T_J, T_{stg}		-55	-	175	°C	

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Thermal and Package Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	Note
Thermal Resistance, Junction to Case	R_{thJC}		-	0.41	0.56	°C/W	Fig. 11
Thermal Resistance, Junction to Ambient	R_{thJA}		-	-	40	°C/W	
Weight	W_T		-	6.34	-	g	
Solder Temperature	T_L	JEDEC J-STD-020	-	-	225	°C	
Mounting Torque	T_M	M3 or 6-32 screw	-	0.9	-	Nm	

Electrical Characteristics (T_c = 25 °C unless otherwise specified)

STATIC CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	Note
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = 100 µA	1200	-	-	V	
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 1200 V, V_{GS} = 0 V	-	1	100	µA	
Gate Threshold Voltage	$V_{GS(th)}$	V_{GS} = V_{DS} , I_D = 25 mA	1.8	2.4	3	V	
Gate-Source Leakage Current	I_{GSS}	V_{GS} = -10 / +25 V, V_{DS} = 0 V	-	-	±100	nA	
Transconductance	g_{fs}	V_{DS} = 10 V, I_D = 40 A	-	20.2	-	S	Fig. 8
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = 20 V, I_D = 40 A	-	25	35	mΩ	Fig. 1
		V_{GS} = 20 V, I_D = 40 A, T_C = 175 °C	-	51	-	mΩ	Fig. 3
		V_{GS} = 18 V, I_D = 40 A	-	27	-	mΩ	Fig. 1
		V_{GS} = 18 V, I_D = 40 A, T_C = 175 °C	-	52	-	mΩ	Fig. 3

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DYNAMIC CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	Note
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 800 V, V_{AC} = 25 mV, f = 100 kHz	-	2250	-	pF	Fig. 10
Output Capacitance	C_{oss}		-	116	-		
Reverse Capacitance	C_{rss}		-	6.5	-		
Gate-Source Charge	Q_{GS}	V_{DS} = 800 V, V_{GS} = -5 / +20 V, I_D = 40 A	-	16	-	nC	Fig. 15
Gate-Drain Charge	Q_{GD}		-	20	-		
Total Gate Charge	Q_G		-	106	-		
Internal Gate Resistance	$R_{G(int)}$	V_{AC} = 25 mV, f = 1 MHz	-	1.3	-	Ω	
Turn-On Switching Energy	E_{ON}	V_{DD} = 800 V, I_D = 40 A, V_{GS} = -5 / +20 V, $R_{G(ext)}$ = 5 Ω, L = 500 µH	-	389	-	µJ	Fig. 16 Fig. 17 Fig. 18
Turn-Off Switching Energy	E_{OFF}		-	81	-		
Total Switching Energy	E_{TOT}		-	470	-		
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 800 V, I_D = 40 A, V_{GS} = -5 / +20 V, $R_{G(ext)}$ = 5 Ω, L = 500 µH Timing relative to V_{DS} Inductive Load	-	13	-	ns	Fig. 19
Rise Time	t_r		-	15	-		
Turn-Off Delay Time	$t_{d(off)}$		-	40	-		
Fall Time	t_f		-	10	-		

BODY DIODE CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	Note
Diode Forward Voltage	V_{SD}	V_{GS} = -5 V, I_{SD} = 40 A	-	4.8	-	V	Fig. 20
		V_{GS} = -5 V, I_{SD} = 40 A, T_J = 175 °C	-	4.4	-	V	Fig. 21
Continuous Diode Forward Current	I_S	V_{GS} = -5 V	-	-	51	A	
Reverse Recovery Time	t_{rr}	V_R= 800 V, I_{SD} = 40 A, V_{GS} = -5 V, di_F/dt = 1000 A/µs	-	22	-	ns	
Reverse Recovery Charge	Q_{rr}		-	117	-	nC	
Peak Reverse Recovery Current	I_{RRM}		-	14	-	A	

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Typical Performance

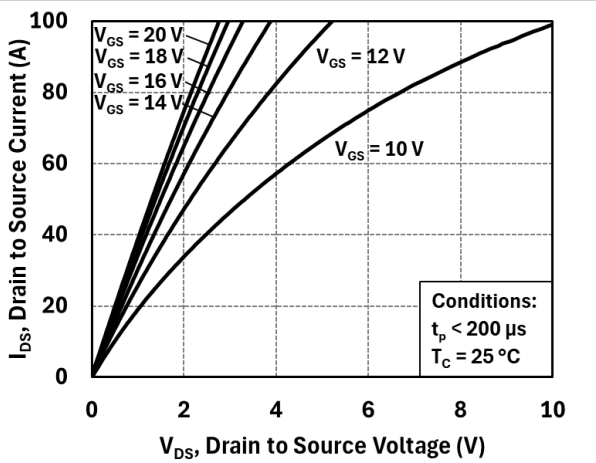

Figure 1: Output Characteristics at 25 °C

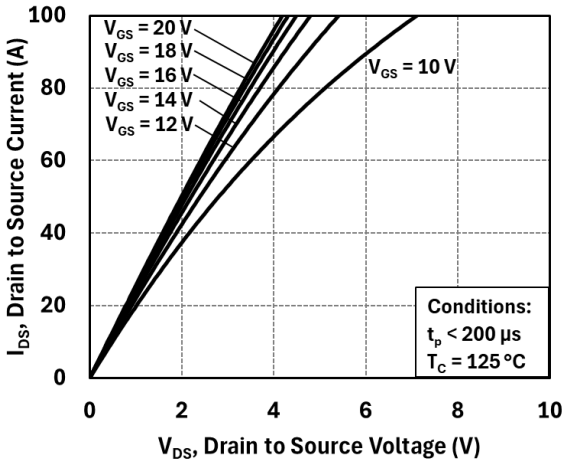

Figure 2: Output Characteristics at 125 °C

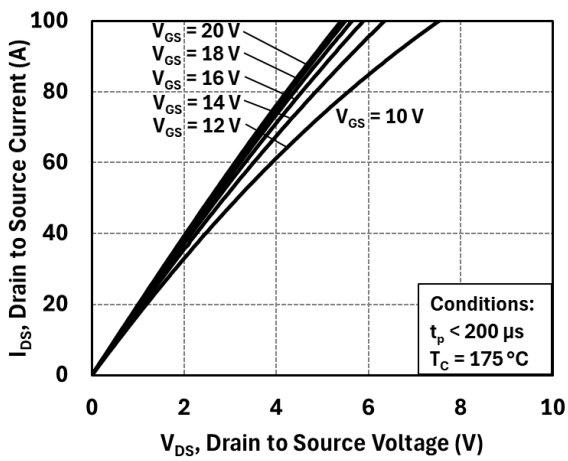

Figure 3: Output Characteristics at 175 °C

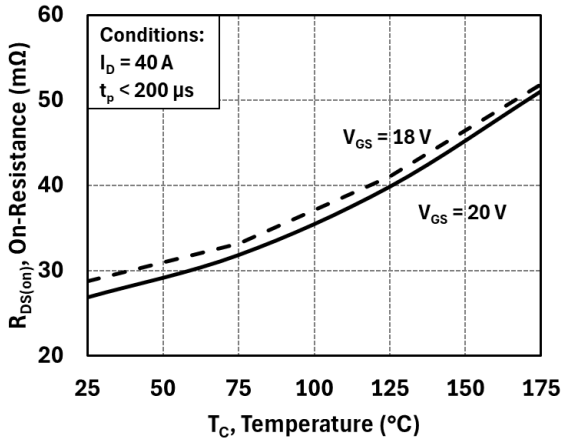

Figure 4: On-Resistance vs. Temperature

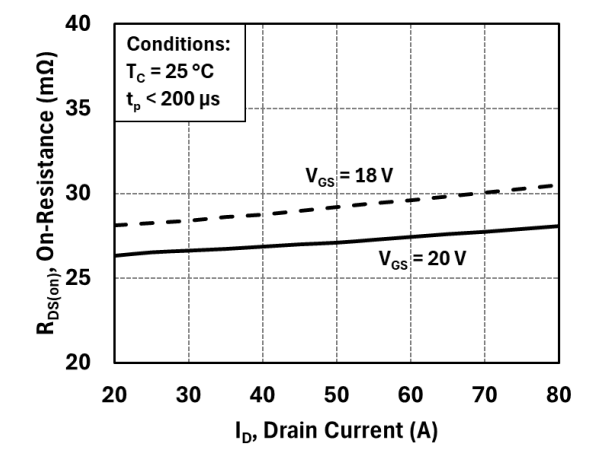

Figure 5: On-Resistance vs. Drain Current

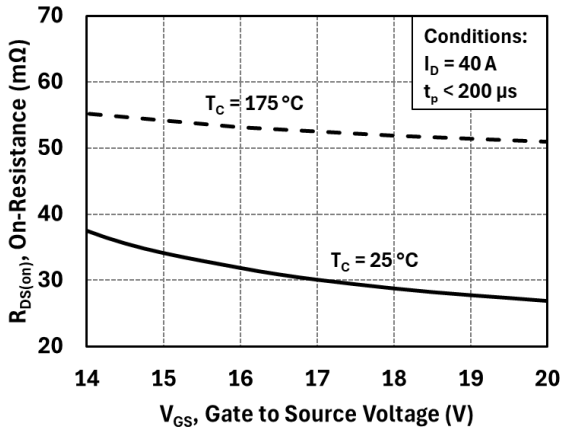

Figure 6: On-Resistance vs. Gate Voltage

Typical Performance

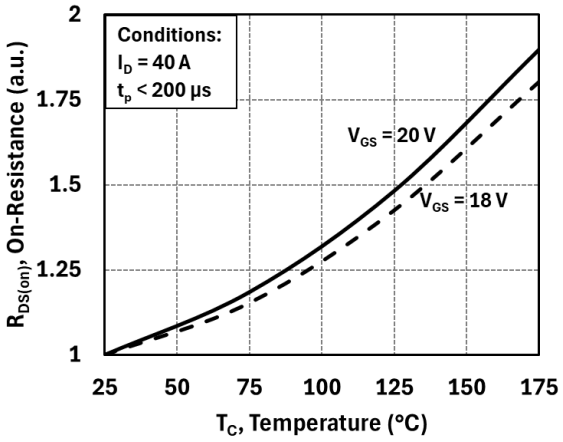

Figure 7: Normalized On-Resistance vs. Temperature

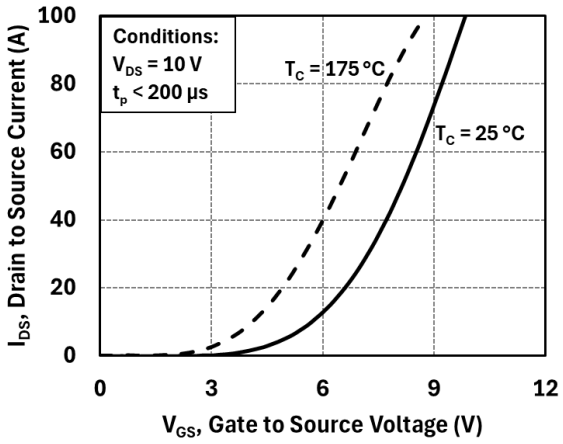

Figure 8: Transfer Characteristics

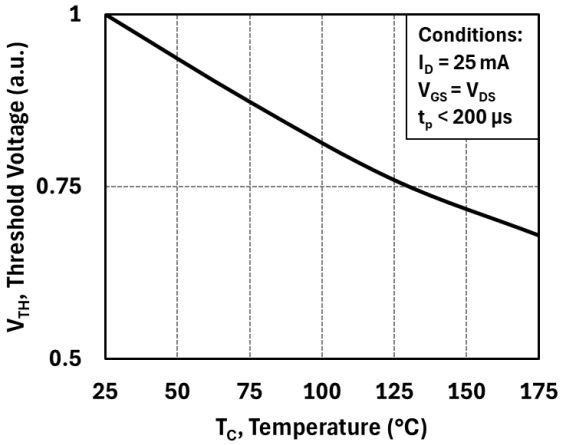

Figure 9: Threshold Voltage vs. Temperature

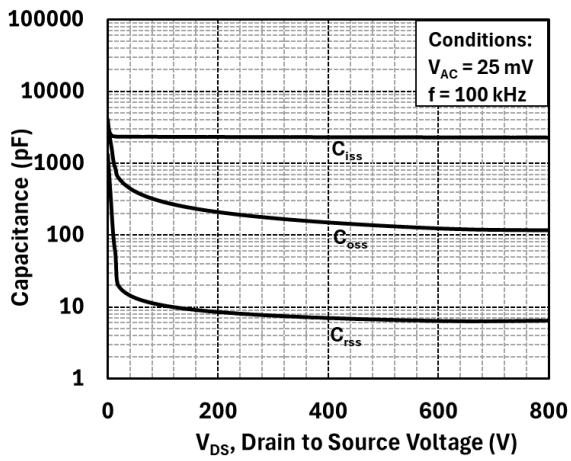

Figure 10: Capacitances vs. Drain-Source Voltage (0-1000 V)

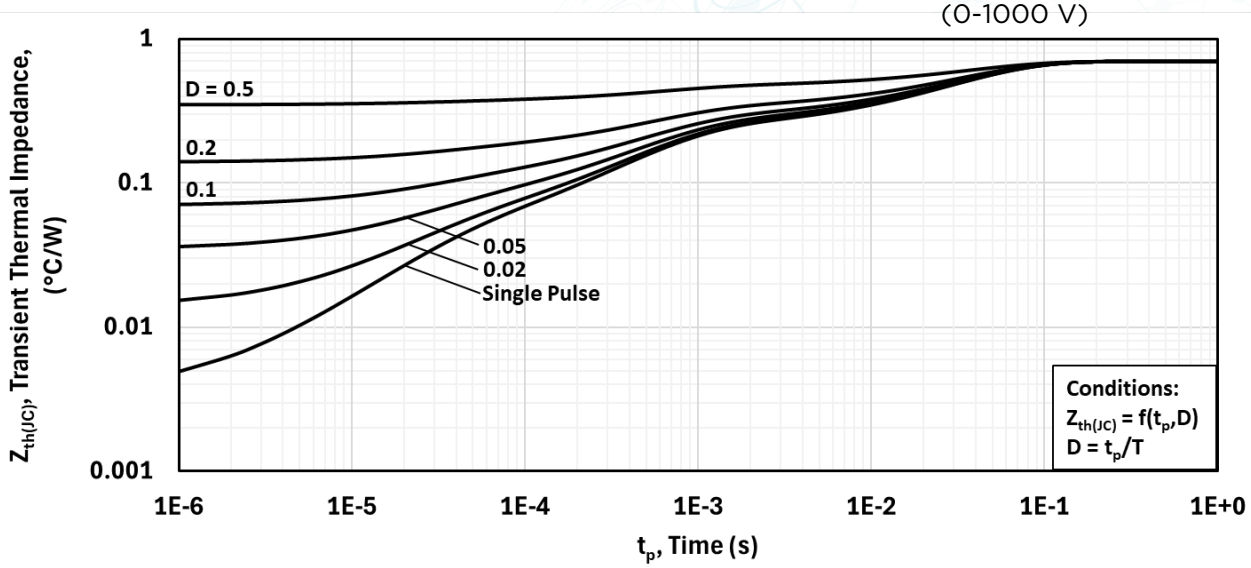

Figure 11: Transient Thermal Impedance

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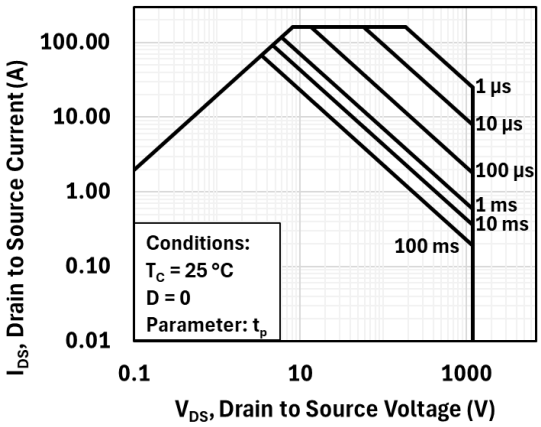

Figure 12: Safe Operating Area

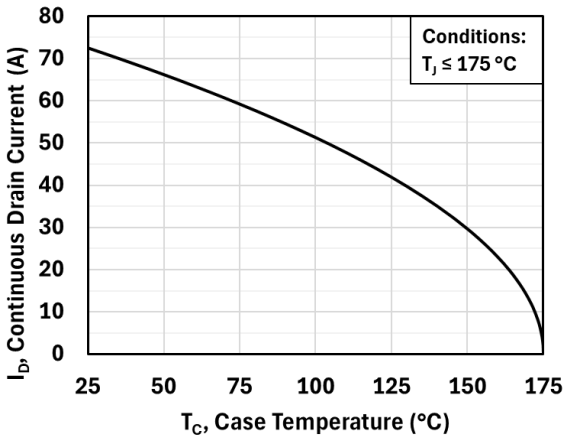

Figure 13: Current De-rating Curve

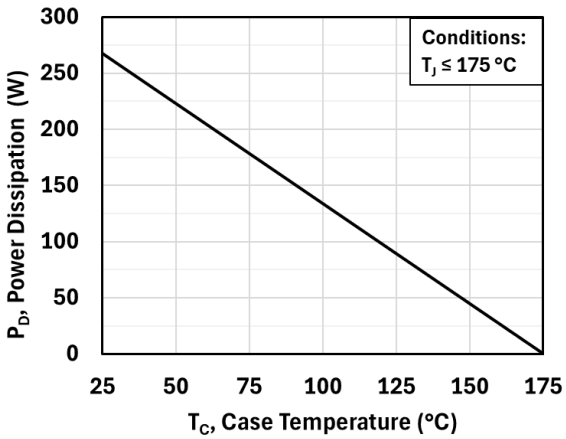

Figure 14: Power De-rating Curve

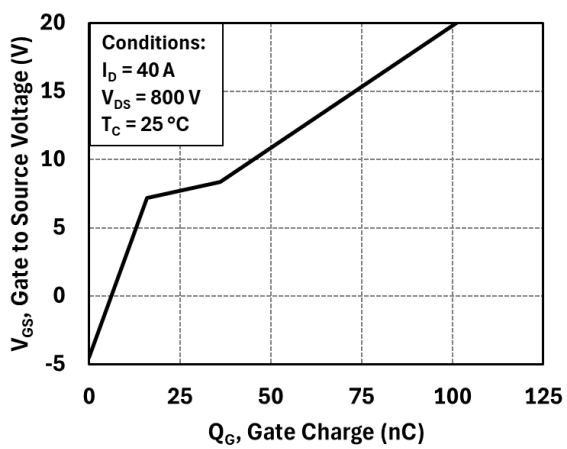

Figure 15: Gate Charge Characteristics

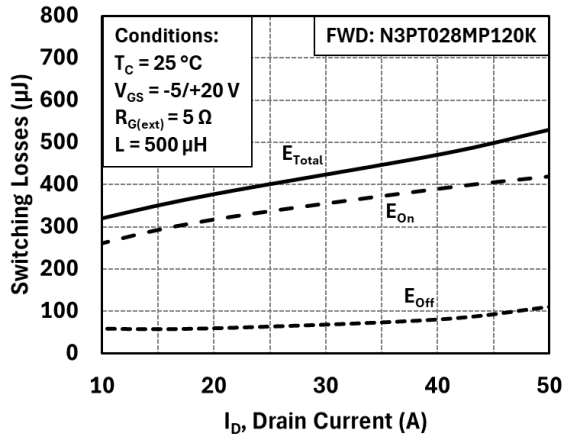

Figure 16: Inductive Switching Energy vs. Drain Current (V_{DD} = 800 V)

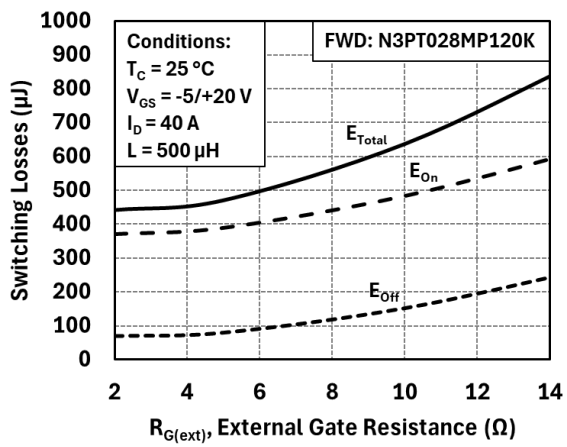

Figure 17: Inductive Switching Energy vs. $R_{G(ext)}$ (V_{DD} = 800 V)

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Typical Performance

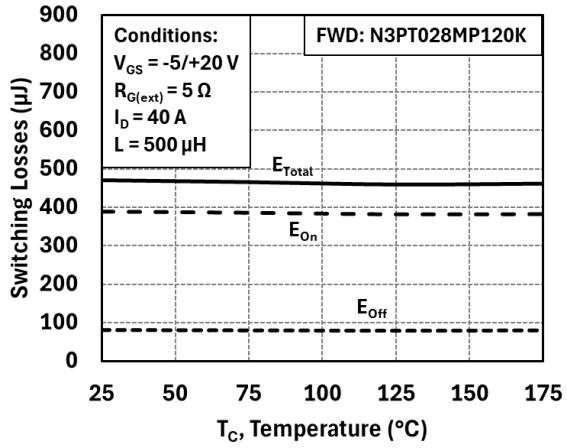

Figure 18: Inductive Switching Energy vs. Temperature (V_{DD} = 800 V)

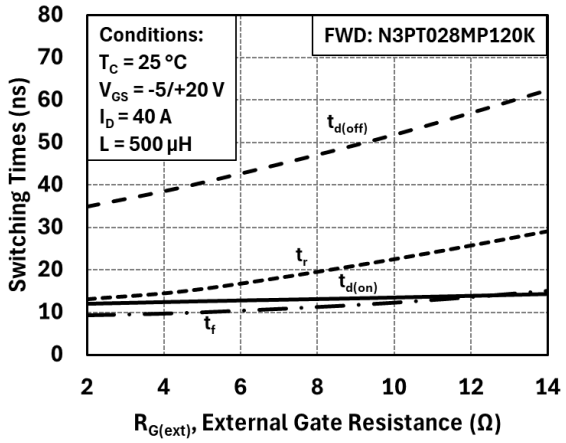

Figure 19: Switching Times vs. $R_{G(ext)}$ (V_{DD} = 800 V)

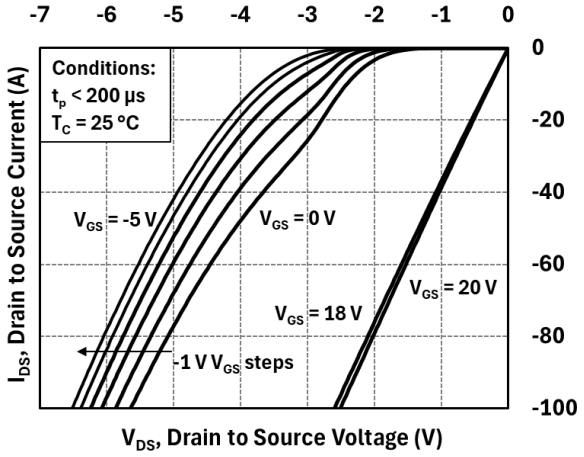

Figure 20: Body Diode Characteristics at 25 °C

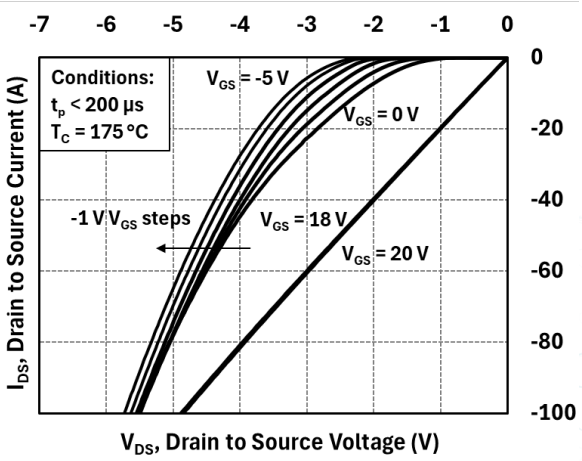

Figure 21: Body Diode Characteristics at 175 °C

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Dynamic Testing Circuit Schematics

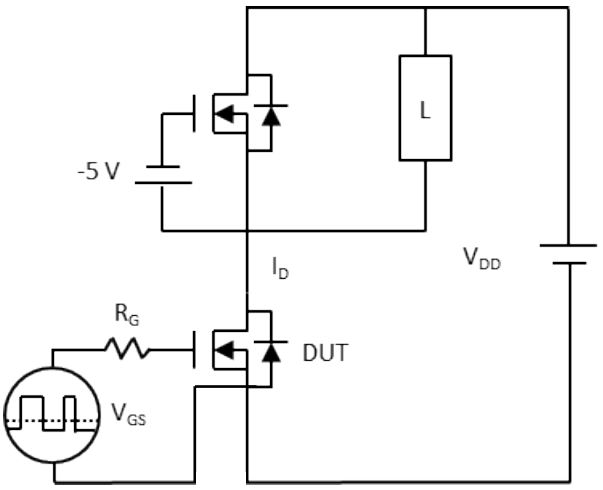


Figure 22: Inductive Load Switching Test Circuit

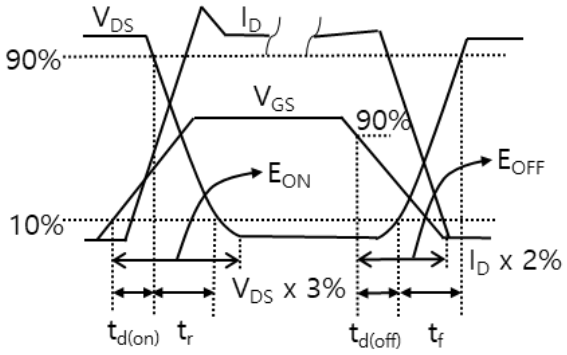


Figure 23: Inductive Load Switching Test Waveforms

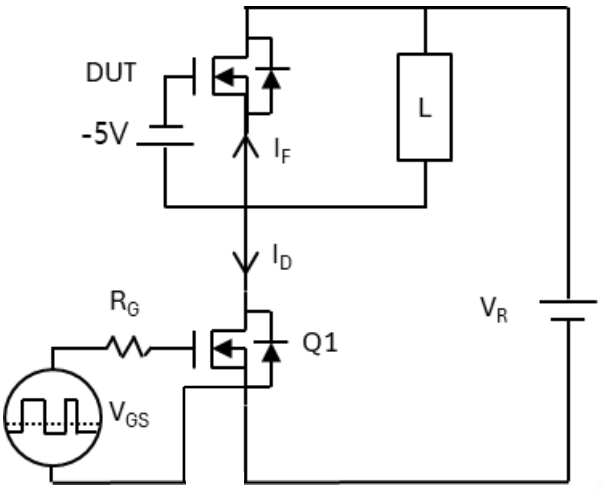


Figure 24: Reverse Recovery Test Circuit

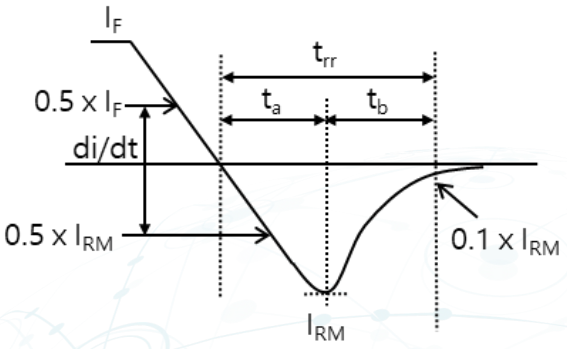


Figure 25: Body Diode Reverse Recovery Test Waveforms

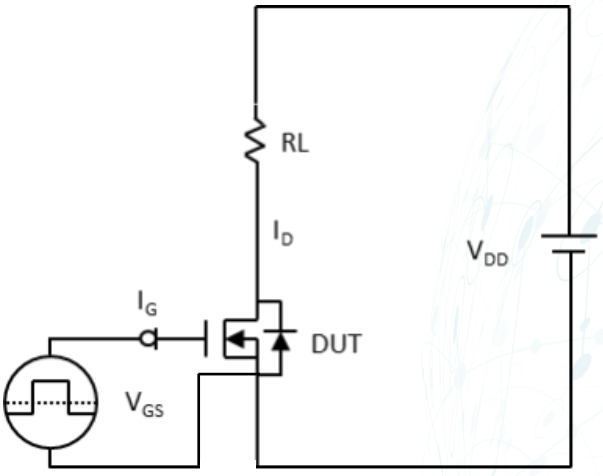


Figure 26: Gate Charge Test Circuit

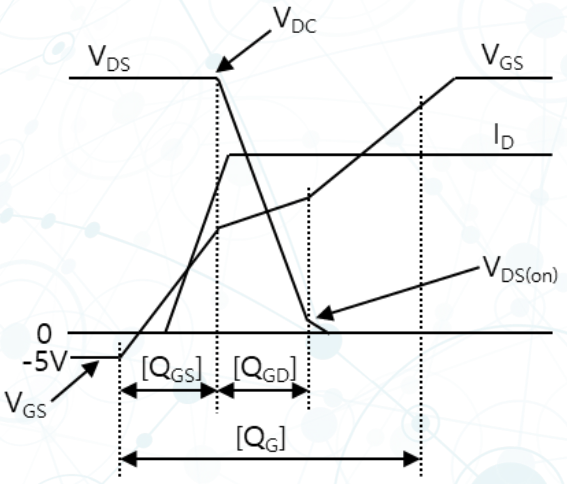
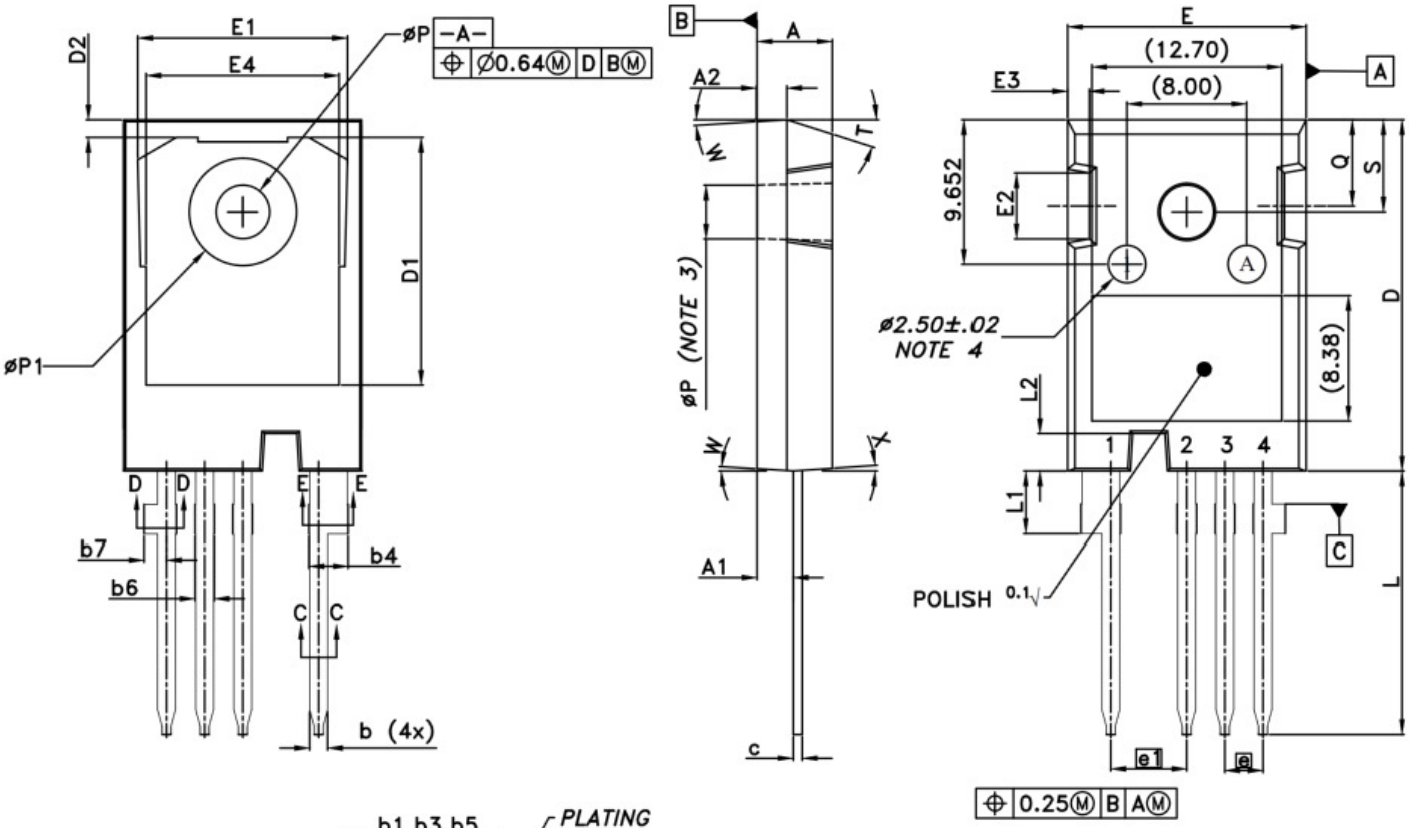
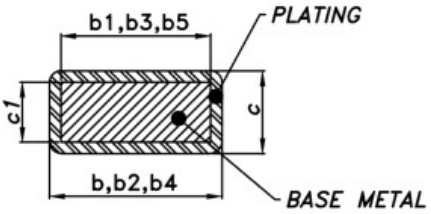


Figure 27: Gate Charge Test Waveforms

Package Dimensions





SECTION C–C, D–D, E–E
NOT TO SCALE

AREA	MIN	NOM	MAX
A	4.83	5.02	5.21
A1	2.29	2.415	2.54
A2	1.86	1.99	2.12
D	23.30	23.45	23.60
D1	15.85	16.55	17.25
D2	1.02	1.17	1.32
E	15.75	15.94	16.13
E1	13.89	14.02	14.15
E2	3.68	4.39	5.10
E3	1.00	1.45	1.90
E4	12.38	12.91	13.43
e		2.540 BSC	
e1		5.080 BSC	
L	17.31	17.57	17.82
L1	3.97	4.17	4.37
L2	2.35	2.50	2.65
b	1.07	–	1.33
b1	1.07	1.20	1.28
b2	2.39	–	2.64
b3	2.39	–	2.69
b4	2.39	–	2.94
b5	2.39	2.53	2.84
b6	1.07	–	1.60
b7	1.30	–	1.70
c	0.55	–	0.68
c1	0.55	0.60	0.65
øP	3.51	3.58	3.65
Q	5.49	5.75	6.00
S	6.04	*6.15*	6.30
øP1		7.18 REF	
T		17.5° REF	
W		3.5° REF	
X		4° REF	

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS
2. DIMENSION D & E DO NOT INLCUDE MOLD FLASH, MOLD FLASH SHALL NOT EXCEED 0.127 MM PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
3. øP TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE TOP OF THE PART WITH A MAXIMUM HOLE DIAMETER OF *3.65mm*.
4. *EJECTION MARK DEPTH* $0.10^{+0.15}_{-0.05}$

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